

CLAIMS

1. An integrated circuit comprising one or several metallization levels, metal conductive strips and metal contact pads being formed on a last metallization level, the last level being covered with a passivation layer in which are formed openings above the contact pads, wherein a thickness of the pads, at least at a level of their portions not
5 covered by the passivation layer, is smaller than the thickness of said conductive strips.

2. The integrated circuit of claim 1, wherein at least one conductive strip forms a coil.
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3. The integrated circuit of claim 1, wherein several of said conductive strips form a supply network.

4. The integrated circuit of claim 1, wherein the last metallization level is formed on an insulating layer, each contact pad being formed of a conductive layer covering an insulating portion laid on the insulating layer.
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5. The integrated circuit of claim 1, wherein the contact pads are made of aluminum.
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6. A method for forming the last metallization level of the integrated circuit of claim 1, comprising:

depositing a metal layer on a substrate;
etching the metal layer to form metal portions and said conductive strips;
25 covering the substrate, the conductive strips, and the metal portions with a passivation layer;
forming openings in the passivation layer above the metal portions; and
partially etching the metal portions to decrease their thickness to obtain said contact pads.

7. A method for forming the last metallization level of the integrated circuit of claim 1, comprising:
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- depositing a metal layer on a substrate;
- etching the metal layer to form metal portions and said conductive strips;
- covering the conductive strips with a protection layer;
- partially etching the metal portions to decrease their thickness to obtain said
- 5 contact pads;
- removing, if necessary, the protection layer;
- covering the substrate, the conductive strips, and the contact pads with a
- passivation layer; and
- forming openings in the passivation layer above the contact pads.